



Dear Valued Customer

Issue date: March 2026 / TG131

Satoshi Fujitani
Director
LSIs Production Headquarters
ROHM Co., Ltd.

Notification of Product/Process Change

Doc. No.: 1026005

This letter intends as a formal notification of change to products which are currently supplied by ROHM Co., Ltd.

ROHM Co., Ltd. requires customers to provide acknowledgment of the receipt of this notification within 30 days from the date of this notice. Lack of acknowledgment of this notice within 30 days is considered as acceptance of the change.

After acknowledgement of the customer, lack of additional response within 90 day period constitutes acceptance of the change according to JEDEC Standard J-STD-046.

Your understanding and cooperation would be highly appreciated.

Issue Date: March 2, 2026

Title of change	Change in wafer factory from ROHM Headquarters to LAPIS Miyagi and change in packaging materials and assembly factory due to production base reorganization.		
Affected product(s)	Manufacturer part number	Customer part number	
	See Attachment	See Attachment	
Detailed description of change	Before	After	
	Front-End Process: ROHM Headquarters 0.18/0.13µm CMOS, 0.13µm EEPROM. Back-End Process: See Attachment.	Front-End Process: LAPIS Miyagi 0.18/0.13µm CMOS, 0.13µm EEPROM. Wire material change model for CMOS products features thicker pad metal. Back-End Process: See Attachment.	
Reason for change	We will restructure low-utilization, small-scale production lines and standardize materials to advance structural reforms that ensure a stable supply to our customers over the long term.		
Anticipated impact on quality	This change will have no impact on product quality.		
Identification of change	It can be identified by the internal model name on the product label.		
Planned first ship date	September 30, 2026	Sample available schedule :	March 2, 2026
Comments			
Supplier contact	Please contact the local ROHM sales office or the authorized distributor.		
Notes			